Nch 30V 2.5A Small Signal MOSFET

V <sub>DSS</sub>	30V
R <sub>DS(on)</sub> (Max.)	67mΩ
I <sub>D</sub>	±2.5A
P <sub>D</sub>	0.8W

1) Low on-resistance

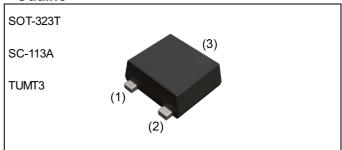
Features

- 2) Built-in G-S Protection Diode
- 3) Small Surface Mount Package (TUMT3)
- 4) Pb-free lead plating; RoHS compliant
- 5) AEC-Q101 Qualified

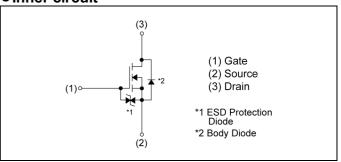
# Application

switching

### Outline



### •Inner circuit



Packaging specifications

	Packing	Embossed Tape
	Reel size (mm)	180
Туре	Tape width (mm)	8
	Basic ordering unit (pcs)	3000
	Taping code	TL
	Marking	PL

# ullet Absolute maximum ratings (T<sub>a</sub> = 25°C ,unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain - Source voltage	V <sub>DSS</sub>	30	V
Continuous drain current	I <sub>D</sub>	±2.5	Α
Pulsed drain current	I <sub>DP</sub> *1	±10	Α
Gate - Source voltage	$V_{GSS}$	±12	V
Power discipation	P <sub>D</sub> *2	0.8	W
Power dissipation	P <sub>D</sub> *3	0.75	W
Junction temperature	T <sub>j</sub>	150	°C
Operating junction and storage temperature range	T <sub>stg</sub>	-55 to +150	°C

# ●Thermal resistance

Deremeter	Cumb of	Values			Lloit
Parameter	Symbol	Min.	Тур.	Max.	Unit
The word reciptores is unation, ambient	R <sub>thJA</sub> *2	-	-	156	°C/W
Thermal resistance, junction - ambient	R <sub>thJA</sub> *3	-	-	167	°C/W

# ● Electrical characteristics (T<sub>a</sub> = 25°C)

Parameter	Symbol Conditions		Values			Unit	
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Offic	
Drain - Source breakdown voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> = 1mA	30	-	-	V	
Breakdown voltage temperature coefficient	$\frac{\Delta V_{(BR)DSS}}{\Delta T_{j}}$	I <sub>D</sub> = 1mA referenced to 25°C	-	29	-	mV/°C	
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>DS</sub> = 30V, V <sub>GS</sub> = 0V	-	-	1	μA	
Gate - Source leakage current	$I_{GSS}$	$V_{GS} = \pm 12V, V_{DS} = 0V$	-	-	±10	μA	
Gate threshold voltage	$V_{GS(th)}$	$V_{DS} = 10V, I_{D} = 1mA$	0.5	-	1.5	V	
Gate threshold voltage temperature coefficient	$\frac{\Delta V_{GS(th)}}{\Delta T_{j}}$	I <sub>D</sub> = 1mA referenced to 25°C	-	-1.6	-	mV/°C	
		V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 2.5A	-	48	67		
Static drain - source on - state resistance	R <sub>DS(on)</sub> *4	V <sub>GS</sub> = 4.0V, I <sub>D</sub> = 2.5A	-	50	70	mΩ	
		$V_{GS} = 2.5V, I_D = 2.5A$	-	70	98		
Gate resistance	R <sub>G</sub> f = 1MHz, open drain		-	7.8	-	Ω	
Forward Transfer Admittance	Y <sub>fs</sub>  *4	$V_{DS} = 10V, I_{D} = 2.5A$	2	-	-	S	

<sup>\*1</sup> Pw $\leq$ 10µs , Duty cycle $\leq$ 1%

<sup>\*2</sup> Mounted on a ceramic board (30×30×0.8mm)

<sup>\*3</sup> Mounted on a FR4 (25×25×0.8mm)

<sup>\*4</sup> Pulsed

# ●Electrical characteristics (T<sub>a</sub> = 25°C)

Darameter	Cymah al	Conditions	Values			Unit
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Input capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0V	-	270	-	
Output capacitance	C <sub>oss</sub>	V <sub>DS</sub> = 10V	-	70	-	pF
Reverse transfer capacitance	C <sub>rss</sub>	f = 1MHz	-	40	-	
Turn - on delay time	t <sub>d(on)</sub> *4	$V_{DD} \simeq 15V, V_{GS} = 4.5V$	-	8	-	
Rise time	t <sub>r</sub> *4	I <sub>D</sub> = 1.25A	-	15	-	
Turn - off delay time	t <sub>d(off)</sub> *4	R <sub>L</sub> ≃ 12Ω	-	27	-	ns
Fall time	t <sub>f</sub> *4	$R_G = 10\Omega$	-	11	-	

# • Gate charge characteristics $(T_a = 25^{\circ}C)$

	\ a	,				
Parameter	Symbol	Conditions		Values		Unit
raiametei	Symbol	Conditions	Min.	Тур.	Max.	Offic
Total gate charge	Qg*4	V <sub>DD</sub> ≃ 15V.	-	3.7	5.2	
Gate - Source charge	Q <sub>gs</sub> *4	V <sub>DD</sub> ≃ 15V, I <sub>D</sub> = 2.5A, V <sub>GS</sub> = 4.5V	-	0.7	-	nC
Gate - Drain charge	Q <sub>gd</sub> *4	V <sub>GS</sub> = 4.5V	-	1.2	-	

# ● Body diode electrical characteristics (Source-Drain) (T<sub>a</sub> = 25°C)

Parameter	Symbol	Conditions	Values			Unit
raianetei	Symbol	Conditions	Min.	Тур.	Max.	Offic
Continuous forward current	I <sub>S</sub>	T = 25°C	-	-	0.6	Α
Pulse forward current	I <sub>SP</sub> *1	T <sub>a</sub> = 25℃	-	-	10	Α
Forward voltage	V <sub>SD</sub> *4	V <sub>GS</sub> = 0V, I <sub>S</sub> = 0.6A	-	-	1.2	V

### • Electrical characteristic curves

Fig.1 Power Dissipation Derating Curve

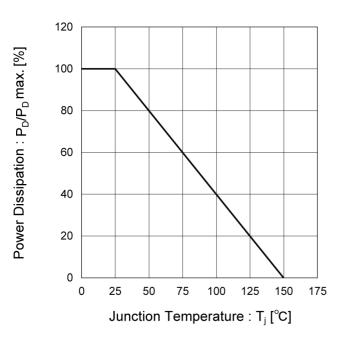
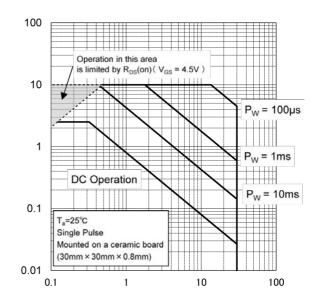


Fig.2 Maximum Safe Operating Area



Drain Current : I<sub>D</sub> [A]

Drain - Source Voltage : V<sub>DS</sub> [V]

Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

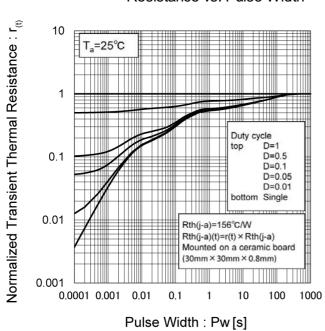
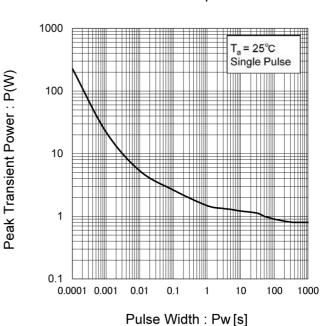


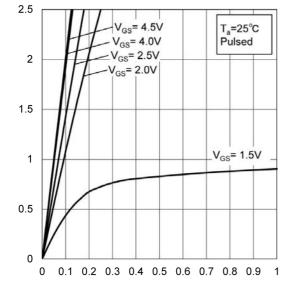
Fig.4 Single Pulse Maximum Power dissipation



Drain Current : I<sub>D</sub> [A]

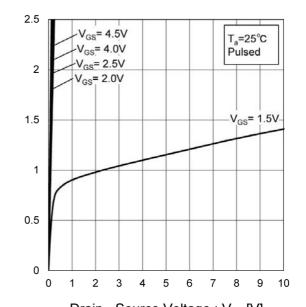
# • Electrical characteristic curves

Fig.5 Typical Output Characteristics(I)



Drain - Source Voltage : V<sub>DS</sub> [V]

Fig.6 Typical Output Characteristics(II)



Drain Current : I<sub>D</sub> [A]

Drain - Source Voltage :  $V_{\text{DS}}[V]$ 

# • Electrical characteristic curves

Fig.7 Breakdown Voltage vs. Junction Temperature

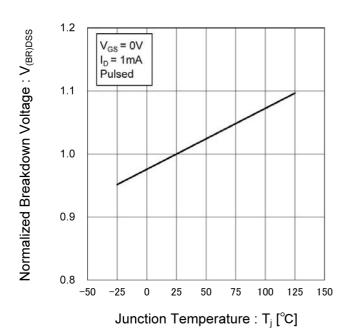


Fig.8 Typical Transfer Characteristics

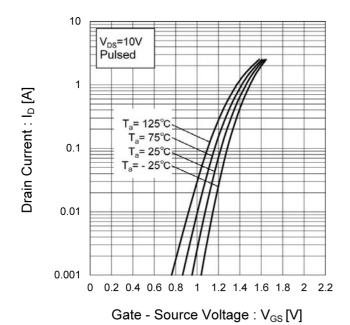
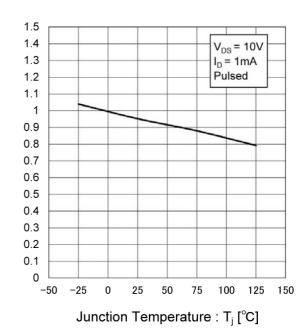


Fig.9 Gate Threshold Voltage vs.
Junction Temperature



Gate Threshold Voltage: VGS(th) [V]

# • Electrical characteristic curves

Fig.10 Forward Transfer Admittance vs.

Drain Current

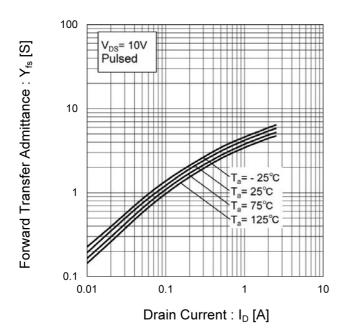
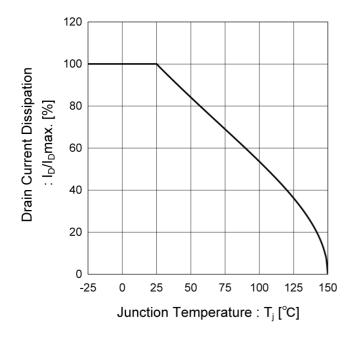


Fig.11 Drain Current Derating Curve



RTF025N03FRA

#### Electrical characteristic curves

Fig.12 Static Drain - Source On - State Resistance vs. Gate Source Voltage

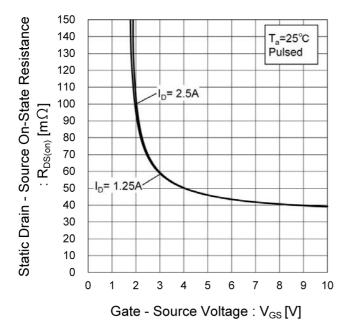


Fig.13 Static Drain - Source On - State Resistance vs. Junction Temperature

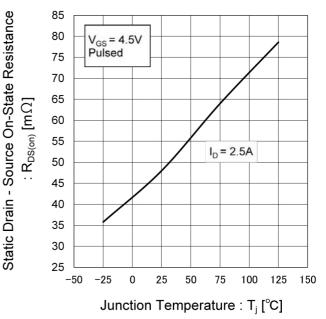
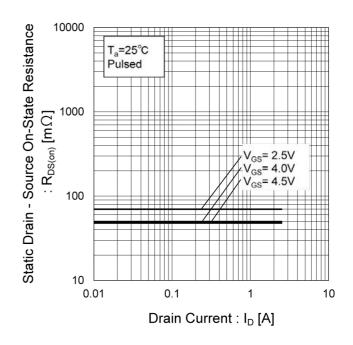


Fig.14 Static Drain - Source On - State Resistance vs. Drain Current (I)

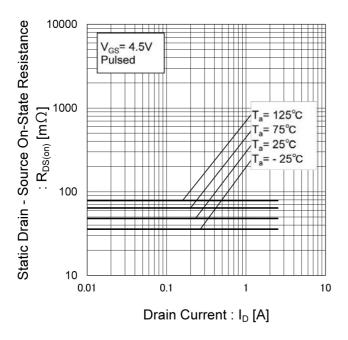


RTF025N03FRA Datasheet

#### Electrical characteristic curves

Fig.15 Static Drain - Source On - State Resistance vs. Drain Current (II)

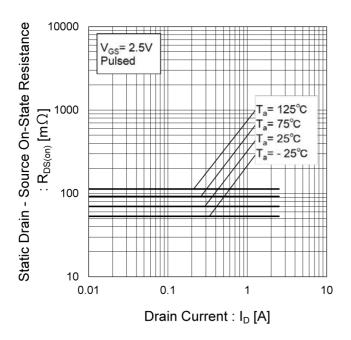
Fig.16 Static Drain - Source On - State Resistance vs. Drain Current (III)

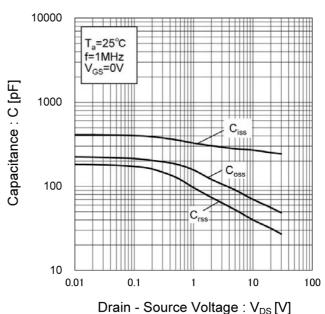


Static Drain Current :  $I_D$  [A]

Fig.17 Static Drain - Source On - State
Resistance vs. Drain Current
(IV)

Fig.18 Typical Capacitance vs.
Drain - Source Voltage





### Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

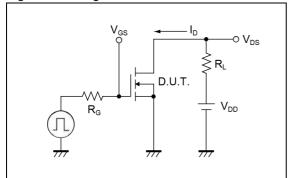


Fig.2-1 Gate Charge Measurement Circuit

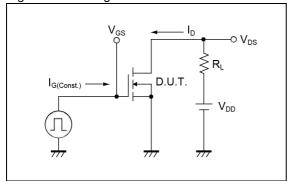


Fig.1-2 Switching Waveforms

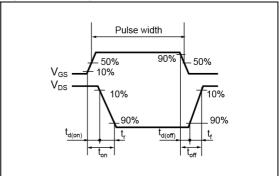
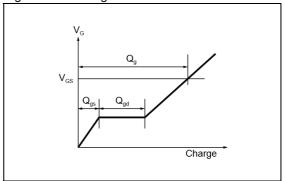


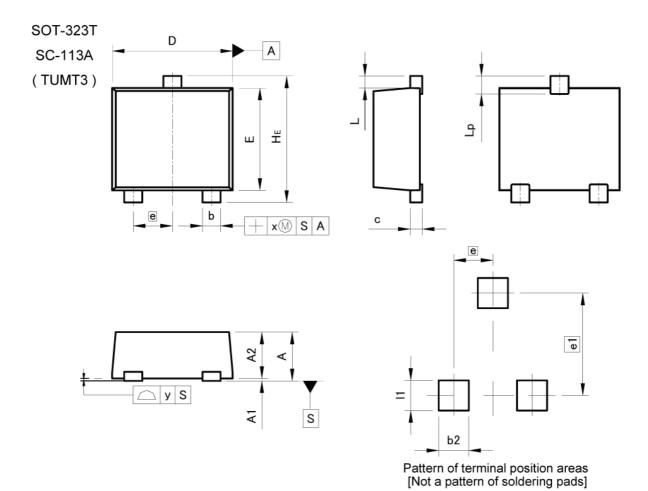
Fig.2-2 Gate Charge Waveform



### Notice

This product might cause chip aging and breakdown under the large electrified environment. Please consider to design ESD protection circuit.

# Dimensions



DIM	MILIM	ETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α	<del>=</del> 0	0.85	· <del></del>	0.033
A1	0.00	0.10	0.000	0.004
A2	0.72	0.82	0.028	0.032
b	0.25	0.40	0.010	0.016
С	0.12	0.22	0.005	0.009
D	1.90	2.10	0.075	0.083
E	1.60	1.80	0.063	0.071
е	0.	65	0.0	26
HE	2.00	2.20	0.079	0.087
L	0.:	20	0.0	08
Lp	25	0.40	72	0.016
х	競	0.10		0.004
у	<del>7</del> .8	0.10	15-	0.004

DIM	MILIM	ETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
b2	223	0.50	822	0.020
e1	1.7	70	0.0	067
11	<del>22</del> 8	0.50	220	0.020

Dimension in mm/inches

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(Note1) Medical Equipment Classification of the Specific Applications

JÁPAN	USA	EU	CHINA
CLASSⅢ	CLASSIII	CLASS II b	CLASSIII
CLASSIV	CLASSIII	CLASSⅢ	CLASSIII

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  - [f] Sealing or coating our Products with resin or other coating materials
  - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
  - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse, is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

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- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

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- 1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
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This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

### **Precaution for Storage / Transportation**

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  - [b] the temperature or humidity exceeds those recommended by ROHM
  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
- Even under ROHM recommended storage condition, solderability of products out of recommended storage time period
  may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is
  exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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